

# SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

# N-Channel Silicon MOSFET ECH8655R — General-Purpose Switching Device **Applications**

Best suited for LiB charging and discharging switch

· Built-in gate protection resistor

Halogen free compliance

# **Features**

- · Low ON-resistance
- 2.5V drive
- Common-drain type
- Protection diode in

# **Specifications**

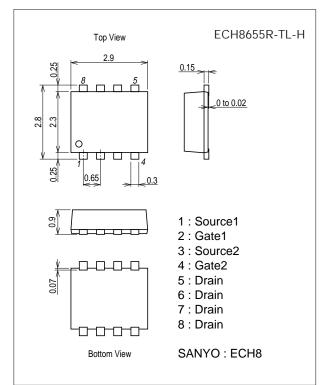
#### Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		24	V
Gate-to-Source Voltage	VGSS		±12	V
Drain Current (DC)	ID		9	А
Drain Current (Pulse)	IDP	PW≤10µs, duty cycle≤1%	60	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm <sup>2</sup> ×0.8mm) 1unit	1.4	W
Total Dissipation	PT	When mounted on ceramic substrate (900mm <sup>2</sup> ×0.8mm)	1.5	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

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#### Package Dimensions

unit : mm (typ) 7011A-003

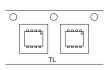


#### **Product & Package Information**

- Package : ECH8
- JEITA, JEDEC
- Minimum Packing Quantity : 3,000 pcs./reel

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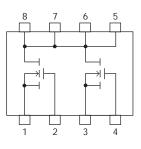
#### Packing Type : TL







#### **Electrical Connection**

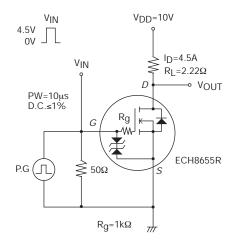


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# Electrical Characteristics at Ta=25°C

Denemation	Currels al		Ratings				
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	24			V	
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±10	μΑ	
Cutoff Voltage	V <sub>GS</sub> (off)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	0.5		1.3	V	
Forward Transfer Admittance	ward Transfer Admittance   yfs   VDS=1		4.8	8		S	
	R <sub>DS</sub> (on)1	ID=4.5A, VGS=4.5V	9	13	17	mΩ	
Statio Drain to Source On State Decistones	R <sub>DS</sub> (on)2	ID=4.5A, VGS=4.0V	9	13.5	18	mΩ	
Static Drain-to-Source On-State Resistance	R <sub>DS</sub> (on)3	ID=4.5A, VGS=3.1V	9.2	15	21	mΩ	
	RDS(on)4	ID=2A, VGS=2.5V	10.5	18	25.5	mΩ	
Turn-ON Delay Time	t <sub>d</sub> (on)			320		ns	
Rise Time	tr			1100		ns	
Turn-OFF Delay Time	t <sub>d</sub> (off)	See specified Test Circuit.		2400		ns	
Fall Time	tf			2100		ns	
Total Gate Charge	Qg			16.8		nC	
Gate-to-Source Charge	Qgs	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V, I <sub>D</sub> =9A		1.6		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		4.8		nC	
Diode Forward Voltage	V <sub>SD</sub>	IS=9A, VGS=0V		0.8	1.2	V	

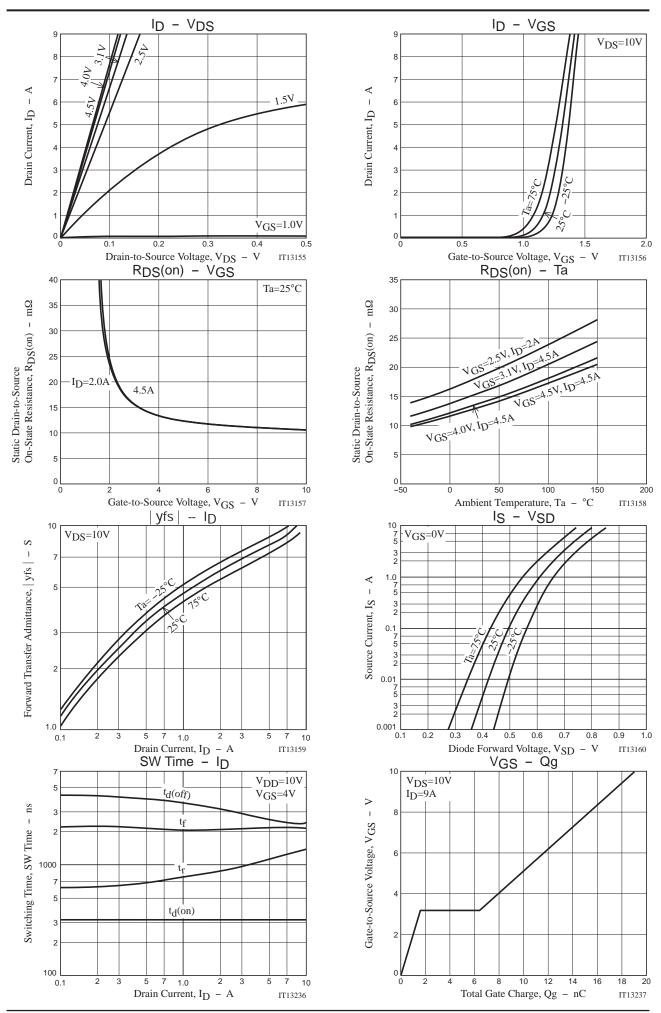
# Switching Time Test Circuit

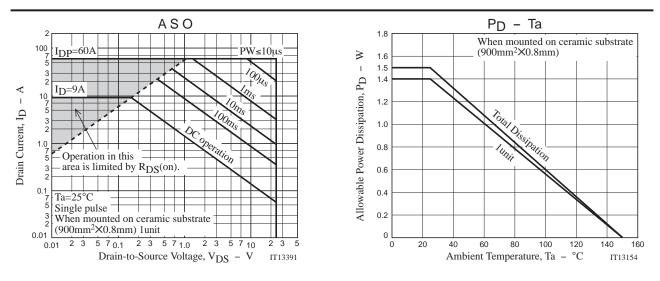


#### **Ordering Information**

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Device	Device Package		memo	
ECH8655R-TL-H	H8655R-TL-H ECH8		Pb Free and Halogen Free	

### ECH8655R





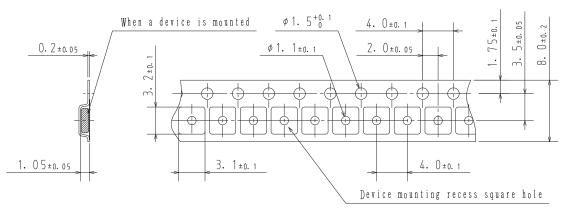
### Embossed Taping Specification ECH8655R-TL-H

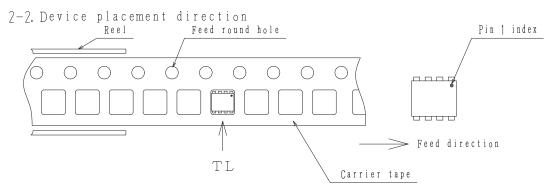
1. Packing Format

ECHO CFHO 3,000 70,000 70,000 1   Dimensions:mm (external) 183×72×185 Dimensions:mm (external)   Packing method (unit:mm) Quartity Quantity   Image: Comparison of a label 108   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label   Image: Comparison of a label	Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing format
EVENTO CTTIC J, 000 J, 000 J, 000 J, 000 J, 000 Jimensions:mm (external) Jimensions:mm (external)   Dimensions:mm (external) 183×72×185 440×195×210   Add over the state of the		Туре	Reel	Inner box	Outer box	Inner BOX $(C-1)$ Outer BOX $(A-7)$
Dimensions:mm (external) Dimensions:mm (external)   183×72×185 440×195×210   Add Ox 195×210 440×195×210   Packing method (unit:mm)   Packing method Outer box label (unit:mm)   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and change in physical distribution process.   Image: Construction of a label and physical distribution process.   Image: Construction of a label and physical distribution process.   Image: Construction of a label and physical distribution process.	ECH8	CPH6	3,000	15,000	90,000	5 reels contained 6 inner boxes contained
Reel label, Inner box label (un it :mm) Outer box label It is a label at the time of factory shipme The form of a label may change in physical distribution process.   Packing method 69 108   Origin 90000000000 110000000000000000000000000		_				Dimensions:mm (external) Dimensions:mm (external)
Packing method (unit:mm)   It is a label at the time of factory shipme The form of a label may change in physical distribution process.   Type No. 69   LOT No. (Unit:minimum minimum mini						183×72×185 440×195×210
treatment of the terminal is lead free. Label JEITA Phase LEAD FREE 3 JEITA Phase 3A	Packing met	Type LOT Quan Orig	No. tity in	-> (P. -> (P. -> (Q. ->	(u: TYPE 0000C IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	nner box label Outer box label   nit:mm) Tis a label at the time of factory shipments.   The form of a label may change in physical distribution process. 108   000000 TYPE CODE   000000 ************************************

2. Taping configuration

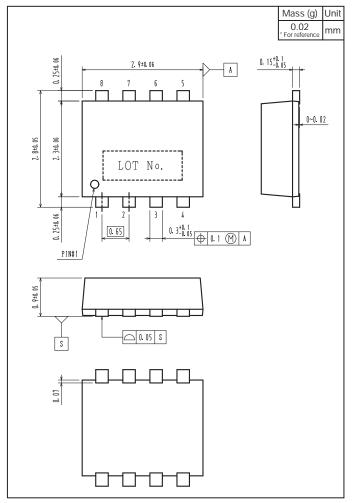
2-1. Carrier tape size (unit:mm)



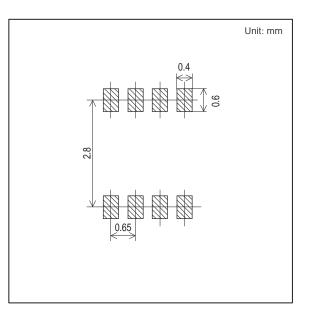


Those with pin 1 index on the feed hole side ·····TL

# Outline Drawing ECH8655R-TL-H



# Land Pattern Example



Note on usage : Since the ECH8655R is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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